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Product group:

Heatsinks and active heatsinks for processors > Heatsinks for LEDs

Heatsinks for LEDs / **ICK LED R 33 x 16,5**   



Ø 33 x 16,5 mm, for IC design LED

Parameters of article ICK LED R 33 x 16,5

R_{th} [K/W]	 13.87
dissipation loss [W]	 8.5
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
Ø [mm]	 33
height [mm]	16.5
plate thickness [mm]	3.5
surface treatment	black anodised

[Technical Drawing](#)

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 D 33**

Thermally conductive foil both sides adhesive / **WLFT 405 D 33**

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